



## Latest Advances and Applications of Infrared Thermography Non-destructive Testing (NDT): 2nd Edition

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### Message from the Guest Editor

Dear Colleagues,

Infrared thermography has undergone a remarkable transformation over the last century, owing to the enormous progress in microsystem technologies of infrared detector design, electronics, and computer science. Currently, thermal imaging plays an essential role in research and development; safety and law enforcement; medicine; wildlife; energy efficiency; and a variety of different fields in the industry, such as condition monitoring, predictive maintenance, and non-destructive testing and evaluation. This Special Issue explores theoretical, numerical, and experimental advances in infrared thermography and its application in a variety of fields. We invite researchers to contribute original research, case studies, industrial and bio-medical applications, and review articles with a focus on the current state of the art.





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## Message from the Editor-in-Chief

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